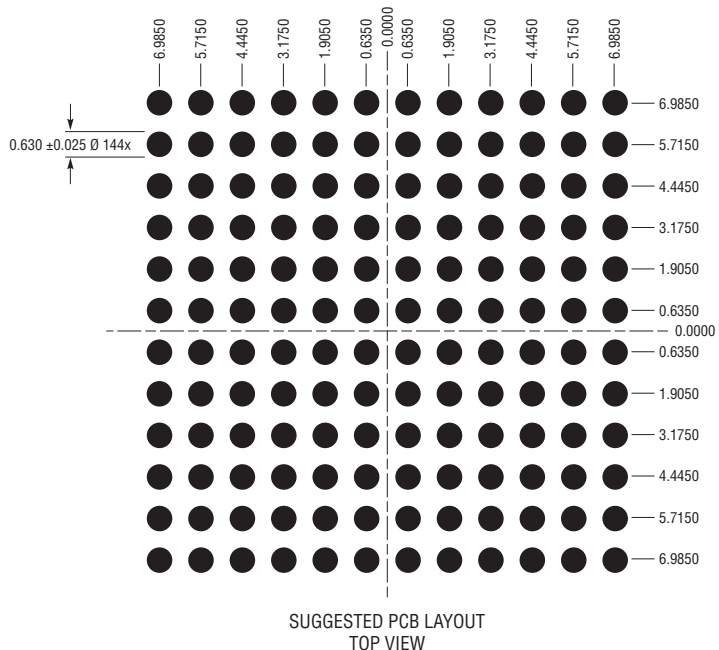
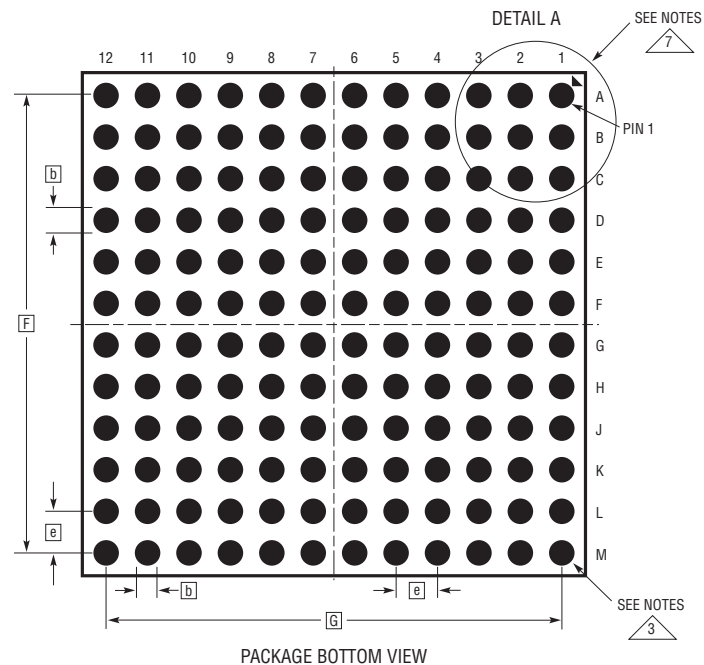
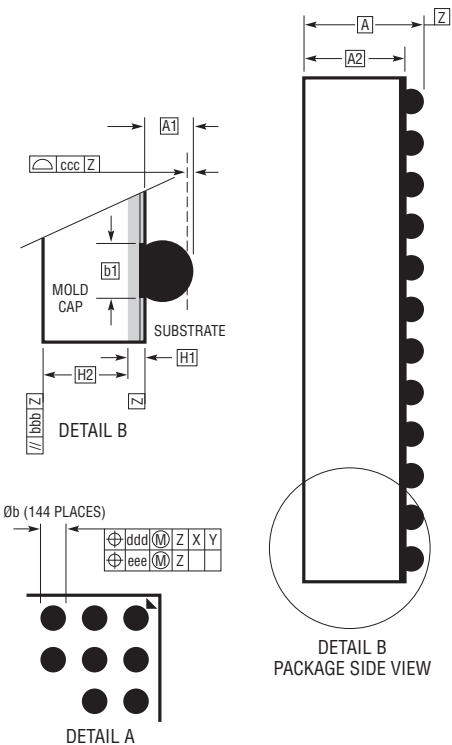
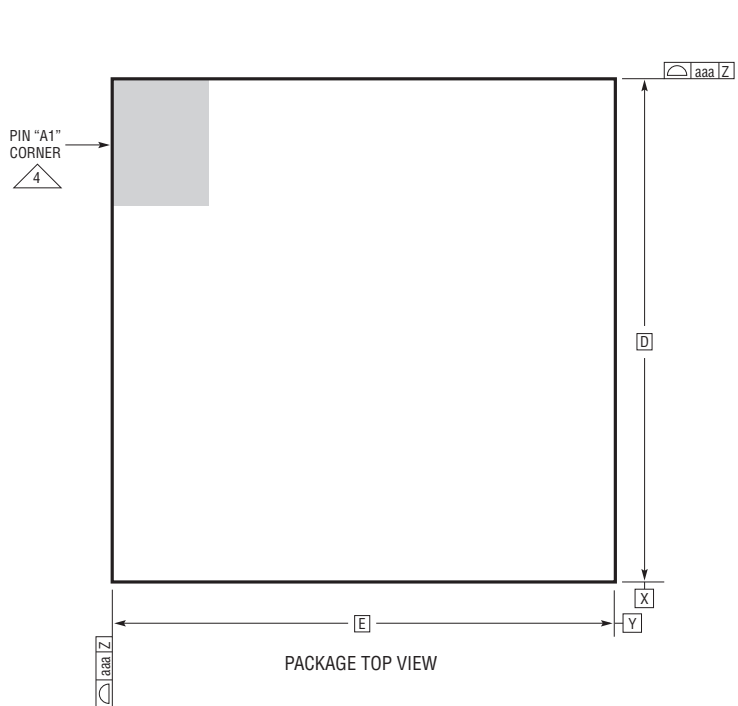


BGA Package
144-Lead (16mm × 16mm × 5.01mm)
 (Reference LTC DWG # 05-08-1920 Rev C)



DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	4.81	5.01	5.21	
A1	0.50	0.60	0.70	BALL HT
A2	4.31	4.41	4.51	
b	0.60	0.75	0.90	BALL DIMENSION
b1	0.60	0.63	0.66	PAD DIMENSION
D	16.00			
E	16.00			
e	1.27			
F	13.97			
G	13.97			
H1	0.36	0.41	0.46	SUBSTRATE THK
H2	3.95	4.00	4.05	MOLD CAP HT
aaa	0.15			
bbb	0.10			
ccc	0.20			
ddd	0.30			
eee	0.15			

TOTAL NUMBER OF BALLS: 144

NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
 2. ALL DIMENSIONS ARE IN MILLIMETERS

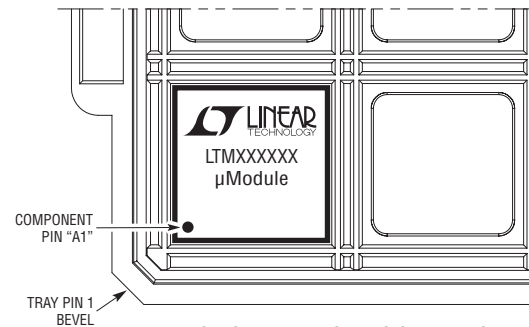
3 BALL DESIGNATION PER JESD MS-028 AND JEP95

4 DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE

5. PRIMARY DATUM -Z- IS SEATING PLANE

6. SOLDER BALL COMPOSITION CAN BE 96.5% Sn/3.0% Ag/0.5% Cu OR Sn Pb EUTECTIC

7 PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



PACKAGE IN TRAY LOADING ORIENTATION